

2023 IEEE Workshop on Microelectronics and Electron Devices (WMED 2023)

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IEEE WMED 2023 Table of Contents

Welcome to the IEEE WMED 2023

Organizing Committee

Technical Program

High School Program

Keynote Address

3-Dimensional Memory Solutions Opening New Experiences for Generations to Come

Naga Chandrasekaran

Keynote Talk

Innovations in Advanced Packaging in the Golden Age of AI

Dr. Akshay Singh

Invited Talks

Spatio-Temporal Learning and Computation in Spiking Neural Networks

Kurtis D. Cantley

Electron Kinetics in Capacitively Coupled Plasmas with Non-Sinusoidal Bias Voltage

Shahid Rauf

Area-Selective Deposition: An Assessment of Current Approaches and Challenges

James R. Engstrom

Processing with Intelligent Storage and Memory – PRISM Center

Tajana Rosing

Tutorials

Extremely Low-Power Logic and Photonics: Challenges and Opportunities

Prof. Mantu K. Hudait

Single-Ended Signaling for Energy-Efficient Short-Reach Communication with High-Bandwidth Density

John Wilson

Special Topics

TCAD and Digital Twins

Raül Camposano

Future of Microsystems Packaging and its Role in Continuing Moore's Law

Madhavan Swaminathan

Invited Paper Session

Single-Ended Signaling for Energy-Efficient Short-Reach Communication with High-Bandwidth Density	1
<i>John M. Wilson</i>	

Atomic Layer Processing of MoS₂	9
<i>Wesley Jen, John D. Hues, Jake Soares, Steven Letourneau, Matthew Lawson, Devika Choudhury, Anil U. Mane, Yu Lu, Yaqiao Wu, Steven M. Hues, Lan Li, Jeffrey W. Elam, and Elton Graugnard</i>	

Contributed Paper Session

Metal-to-Metal Flip-Chip Bonding for High-Temperature 3D SiC IC Integration and Packaging	14
<i>Jiaqi Shi and Feng Li</i>	

An All-Optical 2-Bit Adder Composed of Fabry-Perot Devices.....	18
<i>Jennifer Ellaine Houle, Dennis Sullivan, Ata Zadehgo, and Mark G. Kuzyk</i>	

Power Management Architectures for High Performance NAND Systems.....	22
<i>Luca Nubile, Biagio Iorio, Martin Yu, Jeremy Binfet, Michele Piccardi, Riccardo Cardinali, Walter Di Francesco, and Ali Mohammadzadeh</i>	

R(t)-Based Spike-Timing-Dependent Plasticity in Memristive Neural Networks	26
<i>Farhana Afrin and Kurtis D. Cantley</i>	

Poster Paper Session

Quantum Time-Domain Simulation in 3-D Electron Nano-devices.....	32
<i>Kate Antonov and Dennis Sullivan</i>	

Author Index	36
---------------------------	-----------

Sponsors.....	37
----------------------	-----------